

FEATURES

- | 350W Peak Pulse Power per Line (tp=8/20μs)
- | Protects one power or I/O Port
- | Low Clamping Voltage
- | Low Leakage current

APPLICATIONS

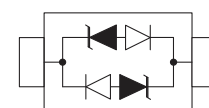
- | Ethernet-10/100/1000 Base T
- | Cellular phones
- | I²C Bus Protection
- | Parallel & Serial Port Protection
- | Personal Digital Assistant (PDA)
- | Microcontroller Input Protection
- | WAN/LAN Equipment



SOD-323



Marking



Schematic Symbol

IEC COMPATIBILITY

- | IEC61000-4-2 (ESD) ±30kV (air), ±30kV (contact)
- | IEC61000-4-4 (EFT) 40A (5/50ns)

APPROVALS

- RoHS** | Compliance with 2011/65/EU
- HF** | Compliance with IEC61249-2-21:2003

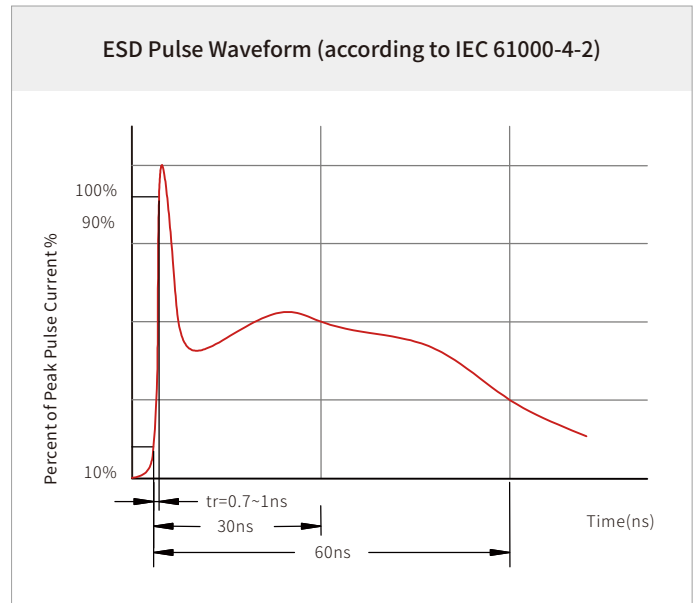
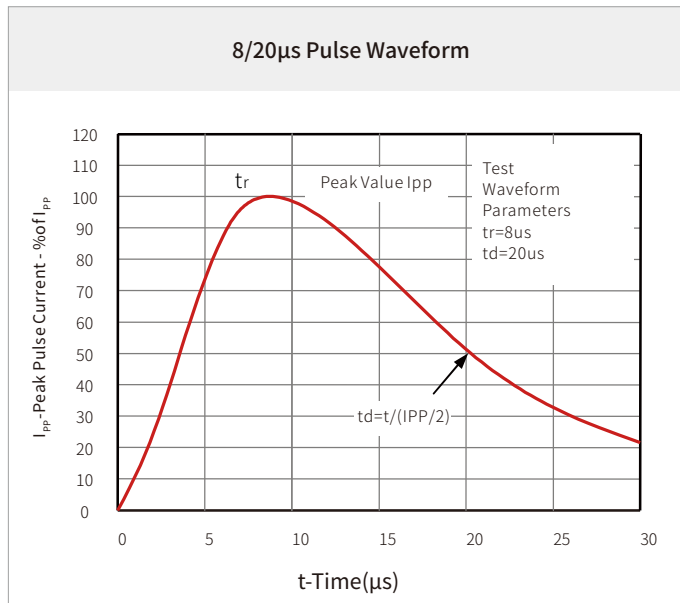
THERMAL CONSIDERATIONS

Symbol	Parameter	Value	Unit
P _{pp}	Peak Pulse Power (tp=8/20μs waveform)	350	Watts
T _J	Operating Temperature Range	-55 to +150	°C
T _{STG}	Storage Temperature Range	-55 to +150	°C

ELECTRICAL CHARACTERISTICS

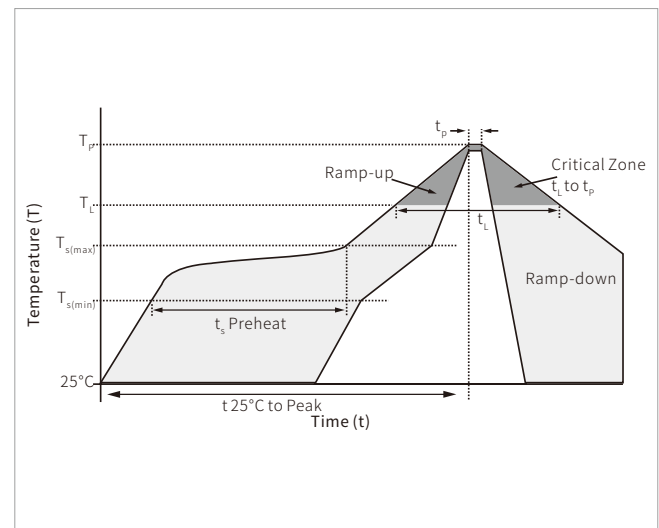
Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
V _{RWM}	Reverse Stand-off Voltage				5	V
V _{BR}	Reverse Breakdown Voltage	I _T =1mA	6			V
I _R	Reverse Leakage Current	V _{RWM} =5V			0.2	μA
V _C	Clamping Voltage	I _{pp} =1A, tp=8/20μs			9.8	V
V _C	Clamping Voltage	I _{pp} =14A, tp=8/20μs			25	V
I _{pp}	Peak Pulse Current	tp=8/20μs			14	A
C _J	Off State Junction Capacitance	V _R =0V, f=1MHz		1.5		pF

CHARACTERISTIC CURVES

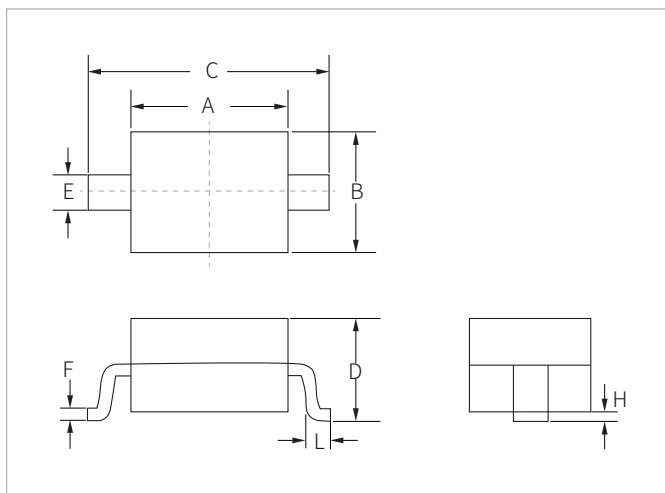


SOLDERING PARAMETERS

Reflow Condition		Lead-free assembly
Pre Heat	Temperature Max ($T_{s(min)}$)	150°C
	Temperature Max ($T_{s(max)}$)	200°C
	Time (min to max) (t_s)	60 – 180 secs
Average ramp up rate (Liquidus Temp (T_L) to peak)		3°C/second max
$T_{s(max)}$ to T_L - Ramp-up Rate		3°C/second max
Reflow	Temperature (T_L) (Liquidus)	217°C
	Time (min to max) (t_L)	60 – 150 seconds
Peak Temperature (T_p)		260°C
Time within 5°C of actual peak Temperature (t_p)		20 – 40 seconds
Ramp-down Rate		6°C/second max
Time 25°C to peak Temperature (T_p)		8 minutes max.
Do not exceed		260°C

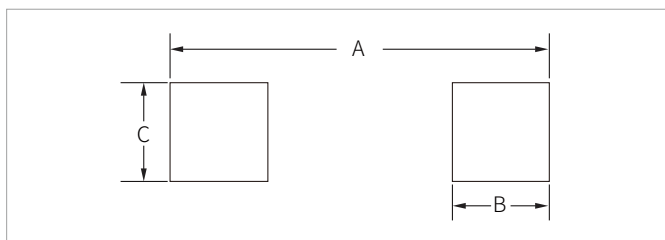


SOD-323 PACKAGE INFORMATION



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	1.60	1.90	0.063	0.075
B	1.15	1.45	0.045	0.057
C	2.35	2.75	0.093	0.108
D	0.80	1.10	0.031	0.043
E	0.25	0.40	0.010	0.016
F	0.10	0.20	0.004	0.008
H	-	0.10	-	0.004
L	0.20	0.40	0.008	0.016

RECOMMENDED PAD LAYOUT DIMENSIONS



Ref.	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	2.87	3.12	0.113	0.123
B	0.66	0.91	0.026	0.036
C	0.66	0.91	0.026	0.036

ORDERING INFORMATION

Part Number	Component Package	QTY/Reel	Reel Size
GBLC05CI	SOD-323	3000PCS	7"

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